TEI0015 TRM

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Table of Contents

- Overview
 - Key Features
 - Block Diagram
 - Main Components
 - Initial Delivery State
 - Configuration Signals
- Signals, Interfaces and Pins
 - I/Os on Pin Headers and Connectors
 - FPGA I/O Banks
 - Micro-USB Connector
 - JTAG Interface
- On-board Peripherals
 - SDRAM
 - o FTDI FT2232H
 - SPI Flash
 - ° EEPROM

 - o ADC
 - o LEDs

 - o Push Bottuns
- Clock Sources Power and Power-On Sequence
 - Power Supply
 - Power Consumption
 - Power Distribution Dependencies
 - Power-On Sequence
 - O Power Rails
 - Bank Voltages
- Technical Specifications
 - Absolute Maximum Ratings
 - Recommended Operating Conditions
 - Physical Dimensions
- Currently Offered Variants
- Revision History
 - Hardware Revision History
 - Document Change History
- Disclaimer
 - Data Privacy
 - Document Warranty
 - Limitation of Liability
 - Copyright Notice
 - Technology Licenses
 - Environmental Protection
 - REACH, RoHS and WEEE

Overview

The Trenz Electronic TEI0015 is a commercial-grade, low cost and small size module integrated with Intel® MAX 10. Intel MAX 10 devices are the ideal solution for system management, I/O expansion, communication control planes, industrial, automotive, and consumer applications.

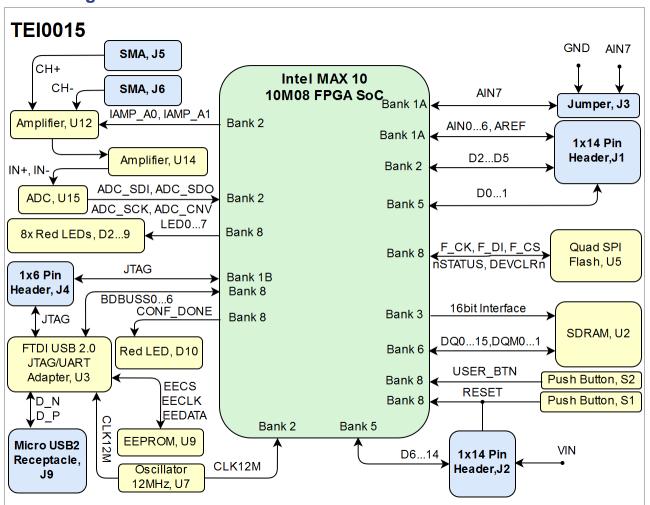
Refer to http://trenz.org/tei0015-info for the current online version of this manual and other available documentation.

Key Features

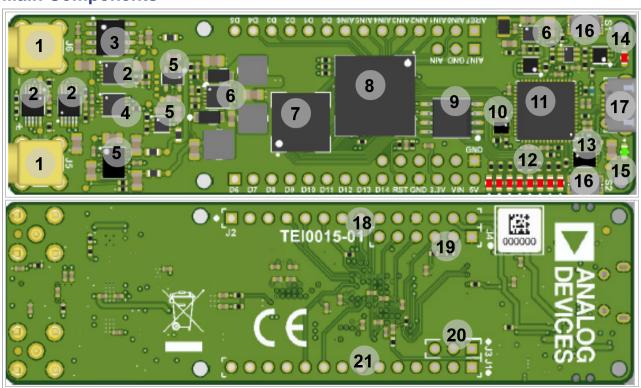
• Intel® MAX 10 Commercial [10M08SAU169C8G]

- o Package: UBGA-169
- Speed Grade: C8 (Slowest)
- Temperature: 0°C to 85°C
- o Package compatible device 10M08...10M16 as assembly variant on request possible
- SDRAM Memory up to 32 Mbyte (8Mbyte default)
- USB 2.0 Multipurpose UART/FIFO IC (FT2232H)
 - o 4 Kbit EEPROM Memory for FTDI configuration data
 - Micro USB Receptacle (communication and power)
- SPI Flash NOT INSTALLED (only special option)
- 8x User LED
- 18 Bit 2MSPS Analog to Digital Converter
- 2x SMA Female Connector
- I/O interface: 23x GPIO Arduino MKR compatible
- Power Supply: 5V
- Dimension: 86.5mm x 25mm
- Others:
 - o Instrumentation Amplifier
 - Differential Amplifier
 - Operational Amplifier

Block Diagram



Main Components



TEI0015 main components

- 1. SMA Connector, J5...6
- 2. Amplifier, U12 U14 U6
- 3. Voltage Reference, U8
- 4. Analog to Digital Converter, U15
- Voltage Regulator, U10 U13 U16
 Switching Voltage Regulator/LDO, U11 U4
 SDRAM Memory, U2
- 8. Intel® MAX 10 FPGA, U1
- SPI Flash Memory, U5
 12.00 MHz MEMS oscillator, U7
- 11. FTDI USB2 to JTAG/UART adapter, U3
- 12. User LEDs, D2...9
- 13. FTDI configuration EEPROM, U9
- 14. Configuration/Status LED (Red), D10
- 15. Power-on LED (Green), D1
- 16. Push button, S1...217. Micro USB Connector, J9
- 18. 1x14 pin header, J2 (Not assembled)
- 19. 1x6 pin header, J4 (Not assembled)20. 1x4 Header, J3 (Not assembled)
- 21. 1x14 pin header, J1 (Not assembled)

Initial Delivery State

| Storage device name | Content | Notes |
|---------------------|---------|-------|
|---------------------|---------|-------|

| Quad SPI Flash | N/A | Not populated |
|----------------|------------|--------------------|
| EEPROM | Programmed | FTDI configuration |

Initial delivery state of programmable devices on the module

Configuration Signals

The FPGA configuration for Intel MAX 10 FPGAs can be stored through JTAG interface (using a *.POF file) on the FPGA itself since the Intel MAX 10 FPGA offers non-volatile configuration memory on chip. The FPGA configuration is loaded from the non-volatile memory when the board is powered up. To configure the FPGA directly, the JTAG interface can be used to configure the FPGA volatile (using a *.SOF file), means the configuration is lost after power off.

FPGA Reconfigration can be triggered by pressing push button S1.

| Signal | Push Button | Pin Header | Note |
|--------|-------------|------------|----------------------|
| RESET | S1 | J2 | Connected to nCONFIG |

Reset process.

Signals, Interfaces and Pins

I/Os on Pin Headers and Connectors

| FPGA Bank | Connector Designator | I/O Signal Count | Voltage Level | Notes |
|--------------|-------------------------|---------------------|------------------|----------------|
| Bank 1A | J1 | 7 | 3.3V | AIN06 |
| Bank 1B | J4 | 5 | 3.3V | JTAG interface |
| Bank 2 | J1 | 4 | 3.3V | DIO25 |
| Bank 5 | J2 | 9 | 3.3V | DIO614 |
| | J1 | 2 | 3.3V | DIO01 |
| Bank 8 | J2 | 1 | 3.3V | RESET |

General I/Os to Pin Headers and connectors information

FPGA I/O Banks

| FPGA Bank | I/O Signal Count | Connected to | Notes |
|--------------|------------------|----------------------|--|
| Bank 1A | 7 | 1x14 Pin header, J1 | AIN06 |
| | 1 | Jumper, J3 | AIN7 |
| Bank 1B | 5 | 1x6 Pin header, J4 | JTAG_EN, TDI, TDO, TMS, TCK |
| Bank 2 | 4 | 1x14 Pin header, J1 | D25 |
| | 5 | A2D, U15 | ADC_EN, ADC_SDI, ADC_SDO, ADC_SCK, ADC_CNV |
| | 1 | 12MHz Oscillator, U7 | CLK12M |
| | 2 | Amplifier, U12 | nIAMP_A0, nIAMP_A1 |

| Bank 3 | 22 | SDRAM, U2 | RAM_ADDR_CMD |
|--------|----|-------------------------------|---|
| Bank 5 | 9 | 1x14 Pin header, J2 | DIO614 |
| | 2 | 1x14 Pin header, J1 | DIO01 |
| | 1 | D12_R | DIO12 |
| Bank 6 | 16 | SDRAM, U2 | DQ015 |
| | 2 | SDRAM, U2 | DQM01 |
| | 1 | D11_R | DIO11 |
| Bank 8 | 8 | User Red LEDs, D29 | LED07 |
| | 6 | SPI Flash, U5 | F_CS, F_CKL, F_DI, F_DO, nSTATUS, DEVCLRn |
| | 1 | Red LED, D10 | CONF_DONE |
| | 6 | FTDI JTAG/UART Adapter, U3 | BDBUS05 |
| | 1 | Push Button, S2 | USER_BTN |

FPGA I/O Banks

Micro-USB Connector

The Micro-USB connector J9 provides an interface to access the FIFO/UART and JTAG functions via FTDI FT2232 chip. The use of this feature requires that FTDI USB drivers are installed on your host PC.

| Pins | Connected to | Note |
|------|-------------------------|------|
| VBUS | USB_VBUS | |
| D+ | FTDI FT2232H U3, DP pin | |
| D- | FTDI FT2232H U3, DM pin | |

Micro USB-2 connector pins

JTAG Interface

JTAG access to the TEI0015 SoM through pin header connector J4. This is normally not needed as there is on-board USB JTAG functionality.

| JTAG Signal | Pin Header Connector | Note |
|-------------|----------------------|-------------------|
| TMS | J4-6 | |
| TDI | J4-5 | |
| TDO | J4-4 | |
| тск | J4-3 | |
| JTAG_EN | J4-2 | Pulled-up to 3.3V |

JTAG pins connection

On-board Peripherals

| Chip/Interface | Designator | Notes |
|----------------|------------|-------|
| | | |

| TEI0015 TRM#SDRAM | U2 | |
|--------------------|----------|-----------------------------|
| FTDI FT2232H | U3 | JTAG/UART/FIFO |
| SPI Flash | U5 | |
| TEI0015 TRM#EEPROM | U9 | |
| Oscillator | U7 | 12 MHz clock source |
| TEI0015 TRM#ADC | U12, U14 | Analog to Digital Converter |
| Push Buttons | \$12 | |
| 8x User LEDs | D29 | Red LEDs |
| | | |

On board peripherals

SDRAM

TEI0015 is equipped with a Winbond 64 MBit (8 MByte) SDRAM chip in standard configuration, variants with 256 Mbit (32 MByte) memory density are also available. The SDRAM chip is connected to the FPGA bank 3 and 6 via 16-bit memory interface with 166MHz clock frequency and CL3 CAS latency.

| SDRAM I/O Signals | Signal Schematic Name | Connected to | Notes |
|----------------------|-----------------------|--------------|-----------------------|
| Address inputs | A0 A13 | bank 3 | - |
| Bank address inputs | BA0 / BA1 | bank 3 | - |
| Data input/output | DQ0 DQ15 | bank 6 | - |
| Data mask | DQM0 DQM1 | bank 6 | |
| Clock | CLK | bank 3 | |
| Control Signals | CS | bank 3 | Chip select |
| | CKE | bank 3 | Clock enable |
| | RAS | bank 3 | Row Address Strobe |
| | CAS | bank 3 | Column Address Strobe |
| | WE | bank 3 | Write Enable |

SDRAM interface IOs and pins

FTDI FT2232H

The FTDI chip U3 converts signals from USB2 to a variety of standard serial and parallel interfaces. Refer to the FTDI data sheet to get information about the features of the FT2232H chip. FTDI FT2232H chip channel A is used in MPPSE mode for JTAG. Channel B is configured to be used in async FIFO mode, this is default mode when using preprogrammed FTDI configuration. In this mode the communication from host PC looks like normal UART but from the FTDI side it is 8 bit FIFO style interface.

The configuration of FTDI FT2232H chip is pre-programmed in the EEPROM U9.

| FTDI Chip U3 Pin | Signal Schematic Name | Connected to | Notes |
|------------------|--------------------------|----------------------|----------------|
| ADBUS0 | тск | FPGA bank 1B, pin G2 | JTAG interface |
| ADBUS1 | TDI | FPGA bank 1B, pin F5 | |
| ADBUS2 | TDO | FPGA bank 1B, pin F6 | |

| TMS | FPGA bank 1B, pin G1 | |
|--------|---|--|
| BDBUS0 | FPGA bank 8, pin A4 | User configurable |
| BDBUS1 | FPGA bank 8, pin B4 | User configurable |
| BDBUS2 | FPGA bank 8, pin B5 | User configurable |
| BDBUS3 | FPGA bank 8, pin A6 | User configurable |
| BDBUS4 | FPGA bank 8, pin B6 | User configurable |
| BDBUS5 | FPGA bank 8, pin A7 | User configurable |
| BDBUS6 | FPGA bank 6, pin C11 | |
| BDBUS7 | FPGA bank 3, pin J7 | |
| BCBUS0 | FPGA bank 5, pin J9 | |
| BCBUS1 | FPGA bank 3, pin K5 | |
| BCBUS2 | FPGA bank 3, pin L4 | |
| BCBUS3 | FPGA bank 3, pin L5 | |
| BCBUS4 | FPGA bank 3, pin N12 | |
| | BDBUS0 BDBUS1 BDBUS2 BDBUS3 BDBUS4 BDBUS5 BDBUS6 BDBUS7 BCBUS0 BCBUS1 BCBUS2 BCBUS3 | BDBUS0 FPGA bank 8, pin A4 BDBUS1 FPGA bank 8, pin B4 BDBUS2 FPGA bank 8, pin B5 BDBUS3 FPGA bank 8, pin A6 BDBUS4 FPGA bank 8, pin B6 BDBUS5 FPGA bank 8, pin A7 BDBUS6 FPGA bank 6, pin C11 BDBUS7 FPGA bank 3, pin J7 BCBUS0 FPGA bank 5, pin J9 BCBUS1 FPGA bank 3, pin K5 BCBUS2 FPGA bank 3, pin L4 BCBUS3 FPGA bank 3, pin L4 |

FTDI chip interfaces and pins

SPI Flash

Optional SPI flash device maybe assembled in custom variants, normally it is not populated.

| Signal Schematic Name | Connected to | Notes |
|--------------------------|---------------------|---|
| F_CS | FPGA bank 8, pin B3 | Chip select |
| F_CLK | FPGA bank 8, pin A3 | Clock |
| F_DI | FPGA bank 8, pin A2 | Data in / out |
| nSTATUS | FPGA bank 8, pin C4 | Data in / out, configuration dual-purpose pin of FPGA |
| DEVCLRN | FPGA bank 8, pin B9 | Data in / out, configuration dual-purpose pin of FPGA |
| F_DO | FPGA bank 8, pin B2 | Data in / out |

Quad SPI Flash memory interface

EEPROM

The configuration of FTDI FT2232H chip is pre-programmed in the EEPROM U9.

| Schematic | Connected to | Notes |
|-----------|---------------------|-------|
| EECS | FTDI U3, Pin EECS | |
| EECLK | FTDI U3, Pin EECLK | |
| EEDATA | FTDI U3, Pin EEDATA | |

I2C EEPROM interface MIOs and pins

ADC

The TEI0015 board is equipped with the Analog Devices AD4003BCPZ-RL7 18-bit 2MSPS ADC.

| Pins | Connected to | Notes |
|------|----------------------------------|-------|
| IN+ | Diff Amplifier U14, VOUT- | |
| IN- | Diff Amplifier U14, VOUT+ | |
| SDI | FPGA, bank 2, pin M2, ADC_SDI | |
| SDO | FPGA, bank 2, pin M1, ADC_SDO | |
| SCK | FPGA, bank 2, pin N3, ADC_SCK | |
| CNV | FPGA, bank 2, pin N2, ADC_CNV | |

A2D converter interface and pins

LEDs

| Designator | Color | Connected to | Active Level | Note |
|------------|-------|--------------|--------------|-------------------------------|
| D29 | Red | LED18 | Active High | User LEDs |
| D10 | Red | CONF_DONE | Active Low | Configuration DONE LED |
| D1 | Green | 3.3V | Active High | After power on it will be on. |

On-board LEDs

Push Bottuns

| Designator | Connected to | Functionality | Note |
|------------|--------------|------------------|---------------------------|
| S1 | RESET | General reset | |
| S2 | USER_BTN | User push button | Connected to FPGA Bank 8. |

On-board Push Buttons

Clock Sources

| Clock Source | Schematic Name | Frequency Note | |
|---------------------|----------------------------|----------------|---------------------------------------|
| MEMS Oscillator, U7 | MEMS Oscillator, U7 CLK12M | | Connected to FTDI FT2232 U3, pin 3. |
| | | | Connected to FPGA SoC bank 2, pin H6. |

Osillators

Power and Power-On Sequence

Power Supply

The module is power supplied from USB (optionally via unpopulated pin header).

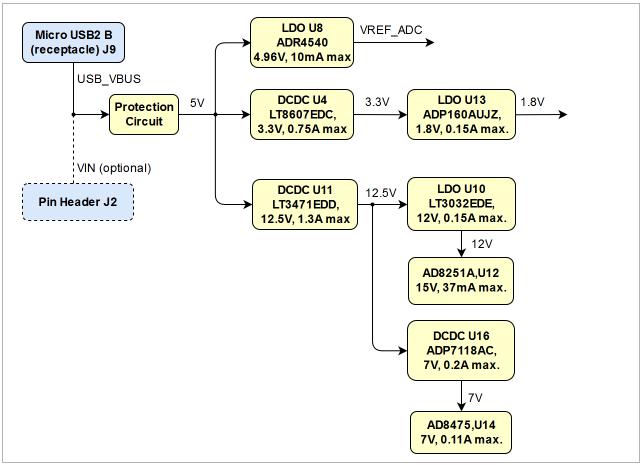
Power Consumption

| FPGA | Typical Current |
|-------------------------|-----------------|
| Intel MAX 10 10M08 FPGA | TBD* |

Power Consumption

Actual power consumption depends on the FPGA design and ambient temperature.

Power Distribution Dependencies



Power Distribution

Power-On Sequence

There is no specific or special power-on sequence, just one single power source is needed. After power on the green LED (D1) will be on.

^{*} TBD - To Be Determined

Power Rails

| Power Rail Name | Connector J2 Pin | Connector J9 Pin | Direction | Notes |
|-----------------|---------------------|---------------------|-----------|---------------------|
| VIN | J2-13 | - | Input | 5 V - Pin Header |
| 3.3V | J2-12 | - | Output | |
| 5V | J2-14 | - | Output | |
| USB_VBUS | - | J9-1 | Input | 5 V - USB Connector |

Module power rails.

Bank Voltages

| Bank | Schematic Name | Voltage | Notes |
|---------|-------------------|---------|-------|
| Bank 1A | VCCIO1A | 3.3V | |
| Bank 1B | VCCIO1B | 3.3V | |
| Bank 2 | VCCIO2 | 3.3V | |
| Bank 3 | VCCIO3 | 3.3V | |
| Bank 5 | VCCIO5 | 3.3V | |
| Bank 6 | VCCIO6 | 3.3V | |
| Bank 8 | VCCIO8 | 3.3V | |

Intel MAX 10 SoC bank voltages.

Technical Specifications

Absolute Maximum Ratings

| Symbols | Description | Min | Max | Unit | Reference Document |
|------------|---|------|------|------|--------------------|
| VIN | Supply voltage | 4.75 | 5.25 | V | |
| CH1-, CH1+ | Analog input voltage on amplifier U12 pin 1, 10 | -30 | 30 | V | AD8251 datasheet |
| T_STG | Storage Temperature | -25 | +85 | °C | |

Absolute maximum ratings

Recommended Operating Conditions

Operating temperature range depends also on customer design and cooling solution. Please contact us for options.

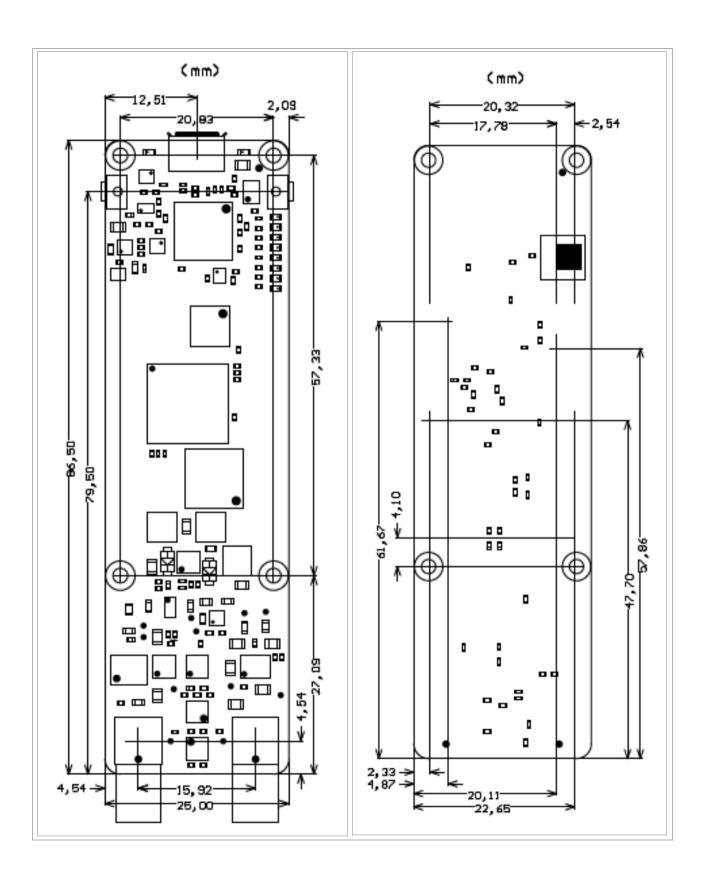
| Symbols | Min | Max | Unit | Reference Document |
|---|------|------|------|-----------------------|
| VIN supply voltage (5.0V nominal) | 4.75 | 5.25 | V | |
| Analog input voltage on amplifier U12 pin 1 (CH1-), 10 (CH1+) | -10 | 10 | V | AD8251 datasheet |
| T_OP | 0 | +70 | °C | W9864G6JT-6 datasheet |

Recommended operating conditions.

Physical Dimensions

Module size: 25 mm \times 86.5 mm. Please download the assembly diagram for exact numbers.

PCB thickness: 1.22 mm.



Physical Dimension

Currently Offered Variants

| Trenz shop TEI0015 overview page | | |
|----------------------------------|-------------|--|
| English page | German page | |

Trenz Electronic Shop Overview

Revision History

Hardware Revision History

| Date | Revision | Changes | Documentation Link |
|------------|----------|---------|--------------------|
| 2019-02-11 | 01 | - | REV01 |

Hardware Revision History

Hardware revision number can be found on the PCB board together with the module model number separated by the dash.



Board hardware revision number.

Document Change History

Error rendering macro 'pageinfo'

Ambiguous method overloading for method jdk. proxy244.\$Proxy3589#hasCon tentLevelPermission. Cannot resolve which method to invoke for [null, class java. lang.String, class com. atlassian.confluence.pages. Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user. ConfluenceUser, class java. lang.String, class com. atlassian.confluence.core. ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core. ContentEntityObject]

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multiple sections updated

| 2020-02-04 | v.98 | ED | | |
|------------|------|----|-------------------------------|--|
| | | | Technical | |
| | | | Specificat | |
| | | | ions | |
| | | | updated | |
| | | | Power | |
| | | | Rails | |
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Document change history.

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REACH, RoHS and WEEE

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Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.

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